



RE944-S3

- Solderable Bread Board 28-Pin-Socket
- Epoxy fibre-glass 1.50 mm
- Single-sided 35 µm Cu
- Hot air leveling (HAL leadfree)
- Solder stop mask
- Adaption circuit board for 28-Pin-Sockets with a distance of 7.62 mm
- Hole spacing 2.54 mm
- 14 three-hole-pads and 2 x 14 two-hole-pads on each side
- U-shape potential strip
- 12 x 16 solder pads Ø 2.20 mm with 2,54 mm grid
- Size 46.99 x 73.02 mm